		lication Fee						
Application Number:	098	09829587						
Filing Date:	09-7	09-Apr-2001						
Title of Invention:	sys	SYSTEM FOR, AND METHOD OF, ETCHING A SURFACE ON A WAFER						
First Named Inventor/Applicant Name:	Pav	Pavel N. Laptev						
Filer:	She	Sheldon R. Meyer/carole wong						
Attorney Docket Number:	TEG	TEGL-01212U50						
Filed as Small Entity								
Utility under 35 USC 111(a) Filing Fees								
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
		2501	1	755	755			
Utility Appl issue fee	1							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1055